MASER
ENGINEERING

DUAL BEAM XENON PLASMA FIB/SEM

- LARGE AREA FIB CROSS-SECTIONING
- LARGE AREA DE-PROCESSING
- (S)TEM SAMPLE PREPERATION
- LARGE AREA TRENCHING FOR FIB-CE
- EDS AND EBSD SAMPLE PREPERATION AND ANALYSIS

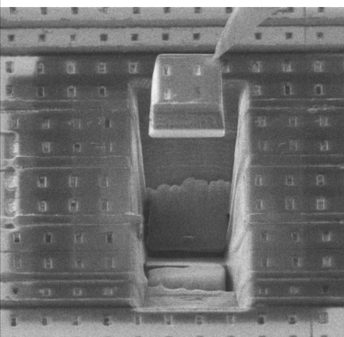
DUAL BEAM XENON PLASMA FIB/SEM

LARGE AREA FIB CROSS-SECTIONING

- MultiChem integrated gas delivery system
- Auto Rocking Mill to prevent curtaining
- Up to hundreds of µm
- Large area slice & view (300 µm x 300 µm)
- Essential tool for 3D device FA

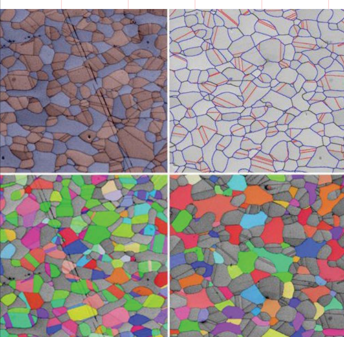
LARGE AREA DE-PROCESSING

- 100µm x 100µm de-processing
- Layer-by-layer de-processing down to 7nm process node
- Damage free single layer exposure
- Secondary Electron auto endpoint detection
- Only reliable solution for sub 20nm process nodes



(S)TEM SAMPLE PREP. AND LARGE AREA TRENCHING FOR FIB-CE

- Down to ~30nm lamella thickness
- Planar TEM Lamella preperation
- Large area stair step trenching for Back-Side FIB Circuit Edit
- System capable of performing FIB circuit edits
- NEXS CAD Navigation for circuit edit



EDS AND EBSD SAMPLE PREPERATION AND ANALYSIS

- High Sensitive EDS detector with <30nm spatial resolution
- Designed for light-element sensitivity and low KV analysis
- Crystallographic and microstructural information for materials science, geological science and advanced device design
- High-sensitivity and high-resolution material analysis

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